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# ***Advanced Etch Technology and Process Integration for Nanopatterning XII***

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# Contents

v *Conference Committee*

---

## ADVANCED PATTERNING INTEGRATION I

---

12499 02 **Enabling process technologies for advanced logic devices beyond FinFET era (Invited Paper)**  
[12499-2]

---

## MATERIALS AND ETCH INTEGRATION

---

12499 03 **AppliedPRO: process recipe optimizer for R&D acceleration and beyond** [12499-44]

12499 04 **Evaluation of TiN hardmask films to prevent line wiggling due to plasma-induced film stress**  
[12499-8]

---

## ADVANCED PATTERNING INTEGRATION II

---

12499 05 **Process optimization for shallow trench isolation etch using computational models** [12499-47]

12499 06 **High-aspect-ratio amorphous carbon mask etch profile control through plasma and surface chemistry optimization** [12499-11]

12499 07 **A method for achieving sub-2nm across-wafer uniformity performance** [12499-45]

12499 08 **Challenges for spacer and source/drain cavity patterning in CFET devices** [12499-13]

12499 09 **Middle-of-line plasma dry etch challenges for CFET integration** [12499-14]

---

## COMPUTATIONAL PATTERNING AND PROCESS CONTROL

---

12499 0A **Computational patterning and process variation impact on photonics devices (Invited Paper)**  
[12499-15]

12499 0B **Variability study of MP18 semi-damascene interconnects with fully self-aligned vias** [12499-16]

12499 0C **A novel approach to etch-process-aware intensive layout retarget** [12499-18]

---

#### NOVEL ATOMIC SCALE PROCESSES

---

- 12499 OD **Radical-based surface treatment and selective etch enabled by high density ICP remote plasma source** [12499-27]
- 12499 OE **Selective isotropic atomic-layer etching of thin films by using dry chemical removal tool** [12499-29]

---

#### SUSTAINABILITY IN ETCH AND PATTERNING INTEGRATION

---

- 12499 OF **Sustainable semiconductor manufacturing: lessons for lithography and etch (Invited Paper)** [12499-31]
- 12499 OG **Advances in low GWP etch gasses (Invited Paper)** [12499-33]
- 12499 OH **Characterization of TSV etch from a sustainability standpoint (Invited Paper)** [12499-34]

---

#### EUV INTEGRATION: JOINT SESSION WITH 12494 AND 12499

---

- 12499 OI **Understanding etch properties of advanced chemically amplified EUV resist** [12499-36]

---

#### POSTER SESSION

---

- 12499 OJ **The damage control of sub layer while ion-driven etching with vertical carbon profile implemented** [12499-40]
- 12499 OK **Study of selective isotropic etching effects of Si<sub>1-x</sub>Ge<sub>x</sub> in gate-all-around nanosheet transistor process** [12499-43]
- 12499 OL **Modeling of SiN<sub>x</sub> growth by chemical vapor deposition in nanosheet indentation** [12499-46]

---

#### DIGITAL POSTER SESSION

---

- 12499 OM **Design of experiment for optimal SiGe-Si selectivity** [12499-12]
- 12499 ON **Opportunities and challenges of heterogeneous integration: from IC packaging POV (Invited Paper)** [12499-20]